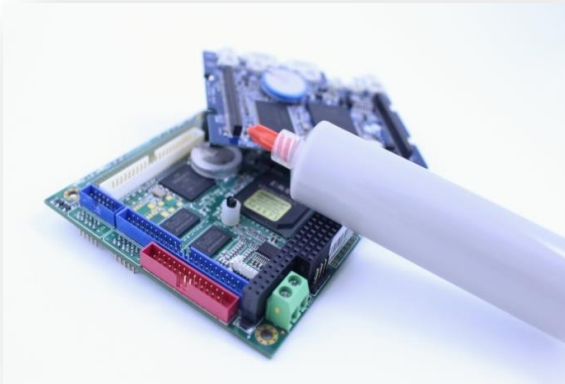


TG-NSP25

Non-Silicone Thermal Putty

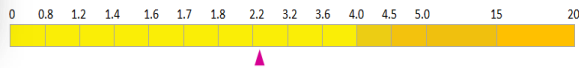


Features

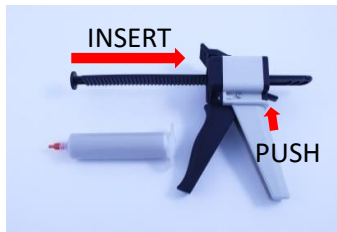
- Silicone free thermal gel
- Shapeable and compressible
- Low thermal resistance
- No fluidity
- Best for north bridge IC

Properties

Thermal Conductivity: 2.5 W/m.K



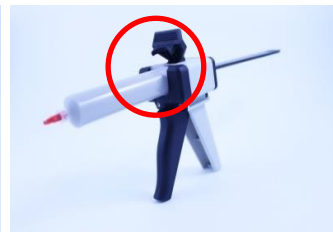
Operation Manual - Gel Gun



STEP1-Push the latch



STEP 2-Put the tube in



STEP3-Close the cover



STEP4-Take off the plug

Reliability

Thermal Impedance	Initial	250 Hr	500 Hr	1000 Hr
80°C Aging	0.124	0.125	0.127	0.126
150°C Aging	0.128	0.129	0.129	0.13
85°C/85% RH	0.126	0.128	0.129	0.131

Physical Properties	TG-NSP25	Unit	Tolerance	Test Method
Thermal Conductivity	2.5	W / mK	±0.25	ASTM D5470
Color	Gray	-	-	Visual
Solid Content	100	%	-	-
Viscosity 0.5rpm	5000	Pa·s	-	Brookfield
Density	2.6	g / cm ³	-	ASTM D792
Low MW Siloxane (D4-10)	0	ppm	-	GC/MS
TML	0.2	%	-	ASTM E595
CVCM	0.1	%	-	ASTM E595
Volume Resistivity	10 ¹⁴	Ohm-cm	-	ASTM D257
Working Temp.	-50 to 150	°C	-	-
Standard package	78g/ 143g/ 1KG	Tube/Pot	-	-

Need Samples?

TGNSP25 - 50 gram

1	2
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1. Choose the P/N
2. Fill the quantity you need

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Thermal Interface Materials: Thermal Pad, Thermal Tape, Thermal Grease, Ceramic Heat Spreader



Version3 20160226